Inverting 3-State Buffer

The NL17SZ240 is a single inverting 3-state buffer in tiny footprint packages.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.7 ns t_{PD} at $V_{CC} = 5 V (typ)$
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in SC-88A, SC-74A, TSOP-5, SOT-553, SOT-953 and UDFN6 Packages
- Chip Complexity < 100 FETs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

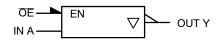


Figure 1. Logic Symbol



ON Semiconductor®

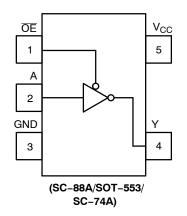
www.onsemi.com

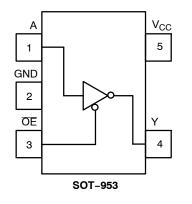
		MARKING DIAGRAMS
	SC-88A (SOT-353) DF SUFFIX CASE 419A	
A	SC-74A DBV SUFFIX CASE 318BQ	
a set	SOT-553 XV5 SUFFIX CASE 463B	XX M• • •
	SOT-953 P5 SUFFIX CASE 527AE	
	UDFN6 1.45 x 1.0 CASE 517AQ	● XM
Ŷ	UDFN6 1.0 x 1.0 CASE 517BX	1 °
X N	X = Specific Devic I = Date Code* = Pb-Free Pack	
*Date (Microdot may be in eith Code orientation and/or epending upon manufac	position may

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

NL17SZ240





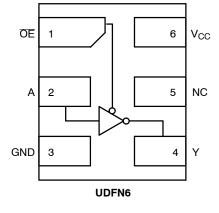


Figure 2. Pinout (Top View)

PIN ASSIGNMENT (SC-88A/SOT-553/SC-74A)

\		,	,
	Pin		Function

FIII	Function
1	ŌĒ
2	А
3	GND
4	Y
5	V _{CC}

PIN ASSIGNMENT (SOT-953)

Function
А
GND
ŌĒ
Y
V _{CC}

PIN ASSIGNMENT (UDFN)

Pin	Function
1	ŌĒ
2	A
3	GND
4	Y
5	NC
6	V _{CC}

FUNCTION TABLE

Inp	Output	
ŌĒ	Α	Y
L	L	Н
L	Н	L
Н	Х	Z

X = Don't Care

MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit	
V _{CC}	DC Supply Voltage		-0.5 to +6.5	V	
V _{IN}	DC Input Voltage		-0.5 to +6.5	V	
	Tri-	(High or Low State) State Mode (Note 1) m Mode (V _{CC} = 0 V)	-0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5	V	
I _{IK}	DC Input Diode Current	nput Diode Current V _{IN} < GND			
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-50	mA	
IOUT	DC Output Source/Sink Current		±50	mA	
I _{CC} or I _{GND}	DC Supply Current per Supply Pin or Ground Pin		±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 secs	260	°C		
TJ	Junction Temperature Under Bias		+150	°C	
θ _{JA}	Thermal Resistance (Note 2)	SC-88A SC-74A SOT-553 SOT-953 UDFN6	659 555 562 560 382	°C/W	
PD	Power Dissipation in Still Air SC-88A SC-74A SOT-553 SOT-953 UDFN6		190 225 222 223 327	mW	
MSL	Moisture Sensitivity		Level 1	-	
F _R	Flammability Rating Ox	ygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-	
V_{ESD}	ESD Withstand Voltage (Note 3) Ch	Human Body Model arged Device Model	2000 1000	V	
I _{Latchup}	Latchup Performance (Note 4)		±100	mA	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

 Applicable to devices with outputs that may be tri-stated.
Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow.
HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.

4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics			Max	Unit
V _{CC}	Positive DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V _{CC} = 0 V)	0 0 0	V _{CC} 5.5 5.5	
T _A	Operating Temperature Range		-55	+125	°C
	Input Rise and Fall Time	$\begin{array}{l} V_{CC} = 1.65 \ V \ to \ 1.95 \ V \\ V_{CC} = 2.3 \ V \ to \ 2.7 \ V \\ V_{CC} = 3.0 \ V \ to \ 3.6 \ V \\ V_{CC} = 4.5 \ V \ to \ 5.5 \ V \end{array}$	0 0 0 0	20 20 10 5	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	Τ,	م = 25°0	C	–55°C ≤ T _A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
VIH	High-Level Input		1.65 to 1.95	0.65 V _{CC}	-	-	0.65 V _{CC}	-	V
	Voltage		2.3 to 5.5	0.70 V _{CC}	-	-	0.70 V _{CC}	-	
VIL	Low-Level Input		1.65 to 1.95	-	-	0.35 V _{CC}	-	0.35 V _{CC}	V
	Voltage		2.3 to 5.5	-	-	0.30 V _{CC}	-	0.30 V _{CC}	
V _{OH}	High-Level Output Voltage	$ \begin{array}{l} V_{IN} = V_{IH} \text{ or } V_{IL} \\ I_{OH} = -100 \ \mu\text{A} \\ I_{OH} = -4 \ \text{mA} \\ I_{OH} = -8 \ \text{mA} \\ I_{OH} = -12 \ \text{mA} \\ I_{OH} = -16 \ \text{mA} \\ I_{OH} = -24 \ \text{mA} \\ I_{OH} = -32 \ \text{mA} \end{array} $	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	$\begin{array}{c} V_{CC} - 0.1 \\ 1.29 \\ 1.9 \\ 2.2 \\ 2.4 \\ 2.3 \\ 3.8 \end{array}$	V _{CC} 1.4 2.1 2.4 2.7 2.5 4.0		V _{CC} - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V _{OL}	Low–Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	- - - - - -	0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55		0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I _{IN}	Input Leakage Current	$V_{IN} = 5.5 V \text{ or GND}$	1.65 to 5.5	-	-	±0.1	-	±1.0	μΑ
I _{OZ}	3-State Output Leakage Current	V _{OUT} = 0 V to 5.5 V	1.65 to 5.5	-	-	±0.5	-	±5.0	μΑ
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	-	-	1.0	-	10	μΑ
ICC	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	-	-	1.0	_	10	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS ($t_R = t_F = 3.0 \text{ ns}$)

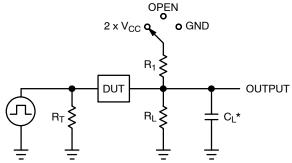
			V_{CC} $T_A = 25^{\circ}C$		С	–55°C ≤ T	_A ≤ 125°C		
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Units
t _{PLH}	Propagation Delay, A to Y	$R_L = 1 M\Omega$, $C_L = 15 pF$	1.65 to 1.95	-	6.0	10	-	10.5	ns
t _{PHL}	(Figures 3 and 4)	$R_L = 1 M\Omega$, $C_L = 15 pF$	2.3 to 2.7	-	6.0	7.5	-	8.0	
		$R_L = 1 M\Omega$, $C_L = 15 pF$	3.0 to 3.6	-	2.5	5.2	-	5.5	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		-	2.9	5.7	-	6.0	
		R_L = 1 MΩ, C_L = 15 pF	4.5 to 5.5	-	2.0	4.5	-	4.8	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		-	2.3	5.0	-	5.3	
t _{PZH}	Output Enable Time,		1.65 to 1.95	-	7.6	9.5	-	10	ns
t _{PZL}	OE to Y (Figures 3 and 4)		2.3 to 2.7	-	3.6	8.5	-	9.0	
			3.0 to 3.6	-	2.8	6.2	-	6.5	
			4.5 to 5.5	-	2.0	5.5	-	5.8	
t _{PHZ}	Output Disable Time,		1.65 to 1.95	-	5.0	10	-	10.5	ns
t _{PLZ}	OE to Y (Figures 3 and 4)		2.3 to 2.7	-	3.3	8.0	-	8.5	
			3.0 to 3.6	-	2.7	5.7	-	6.0	
			4.5 to 5.5	-	2.6	4.7	_	5.0	

NL17SZ240

Symbol Parameter Condition Units Typical C_{IN} Input Capacitance V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} 2.5 pF V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} pF COUT **Output Capacitance** 2.5 10 MHz, V_{CC} = 3.3 V, V_{IN} = 0 V or V_{CC} CPD Power Dissipation Capacitance 9 pF (Note 5) 10 MHz, V_{CC} = 5.5 V, V_{IN} = 0 V or V_{CC} 11

CAPACITIVE CHARACTERISTICS (t_R = t_F = 3.0 ns)

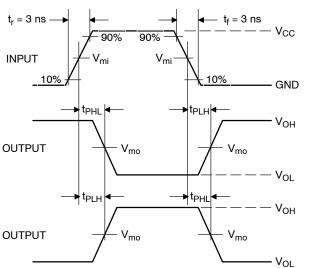
5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.



 R_L, Ω R_1, Ω Test Switch C_L, pF Position See AC Characteristics Table t_{PLH} / t_{PHL} Open 500 t_{PLZ} / t_{PZL} $2 \times V_{CC}$ 50 500 GND 50 500 500 t_{PHZ} / t_{PZH} X = Don't Care

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit



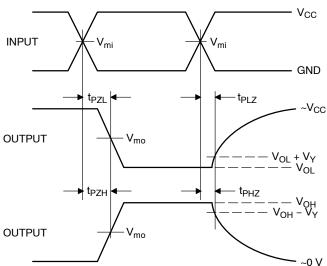


Figure 4. Switching Waveforms

		V _n		
V _{CC} , V	V _{mi} , V	t _{PLH} , t _{PHL}	t _{PZL} , t _{PLZ} , t _{PZH} , t _{PHZ}	V _Y , V
1.65 to 1.95	V _{CC} /2	(V _{OH} – V _{OL})/2	V _{CC} /2	0.15
2.3 to 2.7	V _{CC} /2	(V _{OH} – V _{OL})/2	V _{CC} /2	0.15
3.0 to 3.6	V _{CC} /2	(V _{OH} – V _{OL})/2	V _{CC} /2	0.3
4.5 to 5.5	V _{CC} /2	(V _{OH} – V _{OL})/2	V _{CC} /2	0.3

DEVICE ORDERING INFORMATION

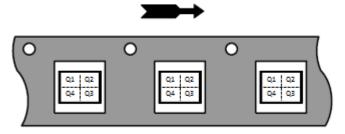
Device	Packages	Marking	Pin 1 Orientation (See below)	Shipping [†]
NL17SZ240DFT2G	SC-88A	U7	Q4	3000 / Tape & Reel
NLV17SZ240DFT1G* (In Development)	SC-88A	U7	Q2	3000 / Tape & Reel
NLV17SZ240DFT2G* (In Development)	SC-88A	U7	Q4	3000 / Tape & Reel
NL17SZ240DBVT1G (In Development)	SC-74A	TBD	TBD	3000 / Tape & Reel
NL17SZ240XV5T2G (In Development)	SOT-553	TBD	TBD	3000 / Tape & Reel
NL17SZ240P5T5G (In Development)	SOT-953	TBD	TBD	4000 / Tape & Reel
NL17SZ240MU1TCG (In Development)	UDFN6, 1.45 x 1.0 x 0.35P	TBD	TBD	3000 / Tape & Reel
NL17SZ240MU3TCG (In Development)	UDFN6, 1.0 x 1.0 x 0.35P	TBD	TBD	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel

Direction of Feed



NSEM



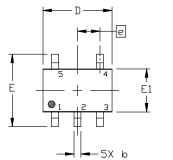
SC-88A (SC-70-5/SOT-353) CASE 419A-02 **ISSUE M**

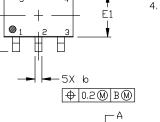
NDTES: 1.

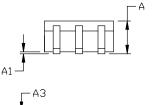
2.

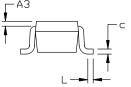
З.

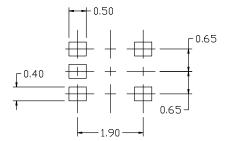
DATE 11 APR 2023











RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

DIM	MILLIMETERS				
MIU	MIN,	NDM.	MAX.		
A	0.80	0.95	1.10		
A1			0.10		
A3	0.20 REF				
b	0.10	0.20	0.30		
С	0.10		0.25		
D	1.80	2.00	5'50		
E	2.00	2.10	5'50		
E1	E1 1.15		1.35		
e	0.65 BSC				
L	0.10	0.15	0.30		

DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,

PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,

OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

CONTROLLING DIMENSION: MILLIMETERS 419A-01 DBSOLETE, NEW STANDARD 419A-02

GENERIC MARKING





*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. CATHODE 2. COMMON ANOD 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4	E
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 1 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to style callout. If style to out in the datasheet r datasheet pinout or p	ype is not called efer to the device
DOCUMENT NUMBER:	98ASB42984B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DESCRIPTION:	SC-88A (SC-70-	PAGE 1 OF 1			

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ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>

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Other Similar products are found below :

LXV200-024SW 74AUP2G34FW3-7 HEF4043BP NL17SG125DFT2G NLU1GT126CMUTCG CD4041UBE 54FCT240CTDB 74HCT540N DS14C88N 070519XB NL17SZ07P5T5G 74LVC2G17FW4-7 CD4502BE 5962-8982101PA 61446R00 74LVCE1G126FZ4-7 NL17SH17P5T5G 74HCT126T14-13 74LVC2G34FW4-7 74VHC9126FT(BJ) RHRXH162244K1 74AUP1G34FW5-7 74LVC1G126FW4-7 74LVC2G126RA3-7 74LVCE1G125FZ4-7 74AUP1G126FW5-7 54FCT240TLB 74LVCE1G07FZ4-7 NLX3G16DMUTCG NLX2G06AMUTCG LE87100NQCT LE87285NQC LE87290YQC LE87290YQCT 74AUP1G125FW5-7 NLU2G16CMUTCG MC74LCX244MN2TWG NL17SG17P5T5G NLV74HC125ADR2G NLVHCT245ADTR2G NLVVHC1G126DFT2G EL5623IRZ ISL1539IRZ-T13 MC100EP17MNG MC74HCT365ADR2G MC74LCX244ADTR2G NL27WZ126US NL37WZ16US NLU1G07MUTCG NLU2G07MUTCG